



IGBT Power Module 1200V/150A

Features

- ◆ 34mm Fast Switching Trench / Field Stop IGBT Technology
- ◆ Low Switching Losses
- ◆ Super Fast Diodes
- ◆ High Short Circuit Capability

Preliminary

Applications

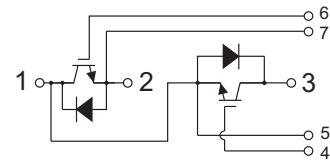
- ◆ Welder / Power Supply
- ◆ UPS / Inverter
- ◆ Industrial Motor Drive



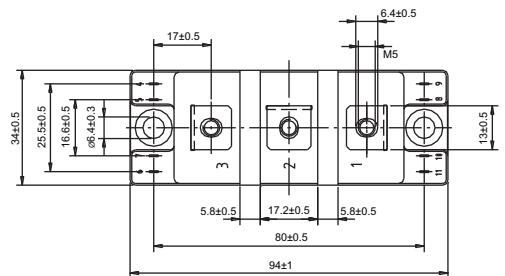
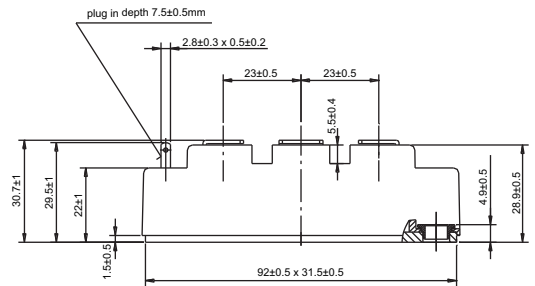
Maximum Ratings (T_C=25°C)

| Item | Symbol | Rated Value | Unit |
|--|---|-------------|------|
| Collector-Emitter Voltage | T _{VJ} = 25°C V _{CES} | 1200 | V |
| Gate-Emitter Peak Voltage | V _{GES} | ±20 | V |
| Continuous DC Collector Current | T _C = 100°C I _{C,nom.} | 150 | A |
| Repetitive Peak Collector Current | t _p = 1ms I _{CRM} | 300 | A |
| Total Power Dissipation | P _{tot} | 790 | W |
| Isolation Voltage | RMS, f=50Hz, t=1min V _{iso} | 3000 | V |
| Continuous DC Forward Current | I _F | 150 | A |
| Repetitive Peak Forward Current | t _p = 1ms I _{FRM} | 300 | A |
| Temperature under switching conditions | T _{VJ op} | -40~+150 | °C |
| Storage Temperature | T _{stg} | -40~+125 | °C |
| Mounting Torque | Module Base to Heatsink (M6) | 3~5 | N.m |
| | Busbar to Terminal (M5) | 2.5~5 | |

Circuit Diagram Headline



Package Outlines



Dimensions in mm (1 mm = 0.0394")



■ Electrical Characteristics ($T_{vj} = 25^{\circ}\text{C}$)

| Characteristics | Symbol | Test Conditions | Min. | Typ. | Max. | Unit |
|--------------------------------------|---------------------|---|------|-------|------|-----------------------------|
| Collector-emitter saturation voltage | $V_{CE\text{ sat}}$ | $I_C = 150\text{A}, V_{GE} = 15\text{V}$ $T_{vj} = 25^{\circ}\text{C}$ | | 1.75 | 2.15 | V |
| | | $I_C = 150\text{A}, V_{GE} = 15\text{V}$ $T_{vj} = 125^{\circ}\text{C}$ | | 2.05 | | |
| | | $I_C = 150\text{A}, V_{GE} = 15\text{V}$ $T_{vj} = 150^{\circ}\text{C}$ | | 2.1 | | |
| Gate threshold voltage | $V_{GE\text{ th}}$ | $I_C = 5.3\text{mA}, V_{CE} = V_{GE}, T_{vj} = 25^{\circ}\text{C}$ | 5.2 | 5.8 | 6.4 | V |
| Gate charge | Q_G | $V_{GE} = -15\text{V} \dots +15\text{V}$ | | 1.994 | | μC |
| Internal gate resistor | $R_{G\text{ int}}$ | $T_{vj} = 25^{\circ}\text{C}$ | | 3 | | Ω |
| Input capacitance | C_{ies} | $f = 1\text{MHz}, T_{vj} = 25^{\circ}\text{C}, V_{CE} = 25\text{V}, V_{GE} = 0\text{V}$ | | 23.8 | | nF |
| Output capacitance | C_{oes} | $f = 1\text{MHz}, T_{vj} = 25^{\circ}\text{C}, V_{CE} = 25\text{V}, V_{GE} = 0\text{V}$ | | 0.625 | | nF |
| Reverse transfer capacitance | C_{res} | $f = 1\text{MHz}, T_{vj} = 25^{\circ}\text{C}, V_{CE} = 25\text{V}, V_{GE} = 0\text{V}$ | | 0.24 | | nF |
| Collector-emitter cut-off current | I_{CES} | $V_{CE} = 1200\text{V}, V_{GE} = 0\text{V}, T_{vj} = 25^{\circ}\text{C}$ | | | 1 | mA |
| Gate-emitter leakage current | I_{GES} | $V_{CE} = 0\text{V}, V_{GE} = 20\text{V}, T_{vj} = 25^{\circ}\text{C}$ | | | 100 | nA |
| Turn-on delay time, inductive load | $t_{d\text{ on}}$ | $I_C = 150\text{A}, V_{CE} = 600\text{V}$ $T_{vj} = 25^{\circ}\text{C}$ | | 0.25 | | μs |
| | | $V_{GE} = \pm 15\text{V}$ $T_{vj} = 125^{\circ}\text{C}$ | | 0.27 | | |
| | | $R_{G\text{ on}} = 1.1\Omega$ $T_{vj} = 150^{\circ}\text{C}$ | | 0.27 | | |
| Rise time, inductive load | t_r | $I_C = 150\text{A}, V_{CE} = 600\text{V}$ $T_{vj} = 25^{\circ}\text{C}$ | | 0.06 | | μs |
| | | $V_{GE} = \pm 15\text{V}$ $T_{vj} = 125^{\circ}\text{C}$ | | 0.07 | | |
| | | $R_{G\text{ on}} = 1.1\Omega$ $T_{vj} = 150^{\circ}\text{C}$ | | 0.075 | | |
| Turn-off delay time, inductive load | $t_{d\text{ off}}$ | $I_C = 150\text{A}, V_{CE} = 600\text{V}$ $T_{vj} = 25^{\circ}\text{C}$ | | 0.4 | | μs |
| | | $V_{GE} = \pm 15\text{V}$ $T_{vj} = 125^{\circ}\text{C}$ | | 0.48 | | |
| | | $R_{G\text{ off}} = 1.1\Omega$ $T_{vj} = 150^{\circ}\text{C}$ | | 0.5 | | |
| Fall time, inductive load | t_f | $I_C = 150\text{A}, V_{CE} = 600\text{V}$ $T_{vj} = 25^{\circ}\text{C}$ | | 0.07 | | μs |
| | | $V_{GE} = \pm 15\text{V}$ $T_{vj} = 125^{\circ}\text{C}$ | | 0.105 | | |
| | | $R_{G\text{ off}} = 1.1\Omega$ $T_{vj} = 150^{\circ}\text{C}$ | | 0.14 | | |
| Turn-on energy loss per pulse | E_{on} | $I_C = 150\text{A}, V_{CE} = 600\text{V}, L_S = 30\text{nH}$ $T_{vj} = 25^{\circ}\text{C}$ | | 2.43 | | mJ |
| | | $V_{GE} = \pm 15\text{V}, di/dt = 3400\text{A}/\mu\text{s} (T_{vj} = 150^{\circ}\text{C})$ $T_{vj} = 125^{\circ}\text{C}$ | | 2.93 | | |
| | | $R_{G\text{ on}} = 1.1\Omega$ $T_{vj} = 150^{\circ}\text{C}$ | | 4.43 | | |
| Turn-off energy loss per pulse | E_{off} | $I_C = 150\text{A}, V_{CE} = 600\text{V}, L_S = 30\text{nH}$ $T_{vj} = 25^{\circ}\text{C}$ | | 8.5 | | mJ |
| | | $V_{GE} = \pm 15\text{V}, du/dt = 3300\text{V}/\mu\text{s} (T_{vj} = 150^{\circ}\text{C})$ $T_{vj} = 125^{\circ}\text{C}$ | | 13.5 | | |
| | | $R_{G\text{ off}} = 1.1\Omega$ $T_{vj} = 150^{\circ}\text{C}$ | | 15.5 | | |
| SC data | I_{SC} | $V_{GE} \leq 15\text{V}, V_{CC} = 800\text{V}$ $V_{CE\text{ max}} = V_{CES} - L_{SCE} \cdot di/dt$ $t_p \leq 10\mu\text{s}, T_{vj} = 150^{\circ}\text{C}$ | | 600 | | A |
| Thermal resistance, junction to case | R_{thJC} | per IGBT | | | 0.19 | $^{\circ}\text{C}/\text{W}$ |
| Thermal resistance, case to heatsink | R_{thCH} | per IGBT | | 0.081 | | $^{\circ}\text{C}/\text{W}$ |
| External gate resistance | $R_{G\text{ ext}}$ | $T_{vj} = 25^{\circ}\text{C}$ | 1.1 | | 10 | Ω |



■ **Diode Ratings & Characteristics**

| Characteristics | Symbol | Test Conditions | Value | Unit |
|---------------------------------|-----------|---|-------|------------------|
| Repetitive peak reverse voltage | V_{RRM} | $T_{vj} = 25^{\circ}C$ | 1200 | V |
| Continuous DC forward current | I_F | | 150 | A |
| Repetitive peak forward current | I_{FRM} | $t_p = 1ms$ | 300 | A |
| I^2t - value | I^2t | $V_R = 0V, t_p = 10ms, T_{vj} = 125^{\circ}C$ | 4100 | A ² s |
| | | $V_R = 0V, t_p = 10ms, T_{vj} = 150^{\circ}C$ | 4000 | |

| Characteristics | Symbol | Test Conditions | Min. | Typ. | Max. | Unit |
|--|-------------|--|------|------|------|---------------|
| Forward voltage | V_F | $I_F = 150A, V_{GE} = 0V$ $T_{vj} = 25^{\circ}C$ | | 2 | 2.2 | V |
| | | $I_F = 150A, V_{GE} = 0V$ $T_{vj} = 125^{\circ}C$ | | 1.9 | | |
| | | $I_F = 150A, V_{GE} = 0V$ $T_{vj} = 150^{\circ}C$ | | 1.9 | | |
| Peak reverse recovery current | I_{RM} | $I_F = 150A, -di_F/dt = 3400A/\mu s$ ($T_{vj} = 150^{\circ}C$) $T_{vj} = 25^{\circ}C$ | | 92 | | A |
| | | $V_R = 600V$ $T_{vj} = 125^{\circ}C$ | | 112 | | |
| | | $V_{GE} = -15V$ $T_{vj} = 150^{\circ}C$ | | 122 | | |
| Recovered charge | Q_r | $I_F = 150A, -di_F/dt = 3400A/\mu s$ ($T_{vj} = 150^{\circ}C$) $T_{vj} = 25^{\circ}C$ | | 10.3 | | μC |
| | | $V_R = 600V$ $T_{vj} = 125^{\circ}C$ | | 20.3 | | |
| | | $V_{GE} = -15V$ $T_{vj} = 150^{\circ}C$ | | 24.3 | | |
| Reverse recovery energy | Erec | $I_F = 150A, -di_F/dt = 3400A/\mu s$ ($T_{vj} = 150^{\circ}C$) $T_{vj} = 25^{\circ}C$ | | 5 | | mJ |
| | | $V_R = 600V$ $T_{vj} = 125^{\circ}C$ | | 8.5 | | |
| | | $V_{GE} = -15V$ $T_{vj} = 150^{\circ}C$ | | 10 | | |
| Reverse Recovery Time | T_{rr} | $I_F = 150A, -di_F/dt = 3400A/\mu s, V_R = 600V, V_{GE} = -15V, T_{vj} = 25^{\circ}C$ | | 88 | | ns |
| Thermal resistance, junction to case | R_{thJC} | per diode | | | 0.31 | $^{\circ}C/W$ |
| Thermal resistance, case to heatsink | R_{thCH} | per diode | | 0.13 | | $^{\circ}C/W$ |
| Temperature under switching conditions | $T_{vj op}$ | | -40 | | 150 | $^{\circ}C$ |

■ **Module Ratings & Characteristics**

| Characteristics | Symbol | Test Conditions | Value | Unit |
|------------------------------|--------|---------------------------------------|-----------|------|
| Material of module baseplate | | | Cu | |
| Internal isolation | | basic insulation (class 1, IEC 61140) | Al_2O_3 | |
| Creepage distance | | terminal to heatsink | 17 | mm |
| | | terminal to terminal | 20 | |
| Clearance | | terminal to heatsink | 17 | mm |
| | | terminal to terminal | 9.5 | |
| Comperative tracking index | CTI | | >200 | |



Typical Characteristics

Preliminary Data

Fig.1 Output characteristic IGBT, Inverter (typical)

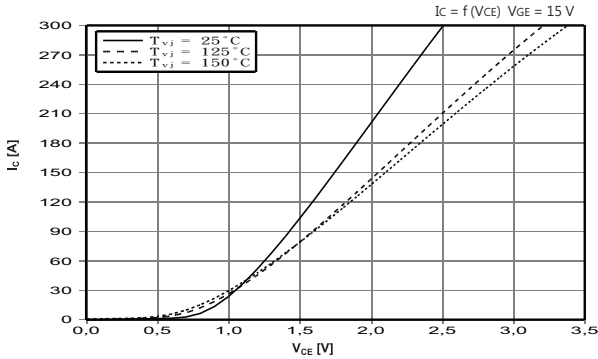


Fig.2 Output characteristic IGBT, Inverter (typical)

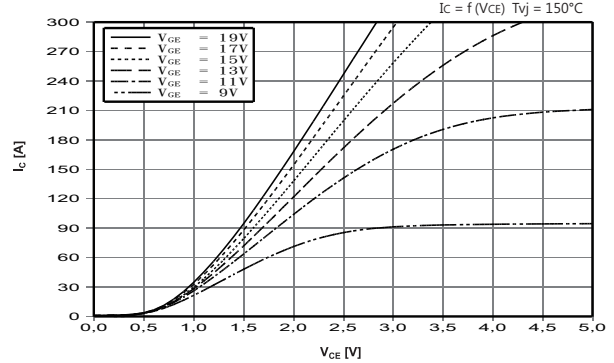


Fig.3 Transfer characteristic IGBT, Inverter (typical)

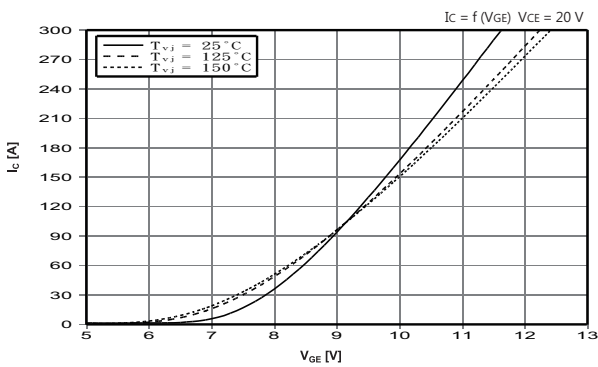


Fig.4 Switching losses IGBT, Inverter (typical)

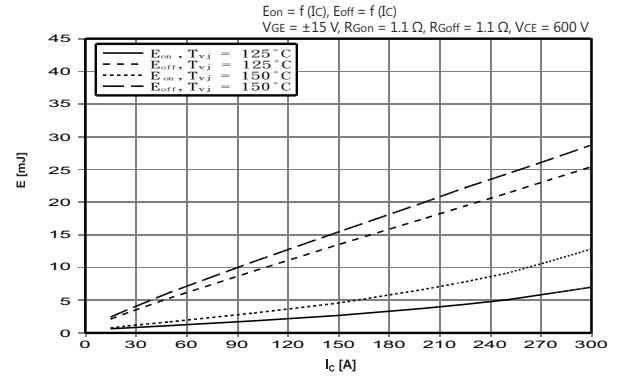


Fig.5 Switching losses IGBT, Inverter (typical)

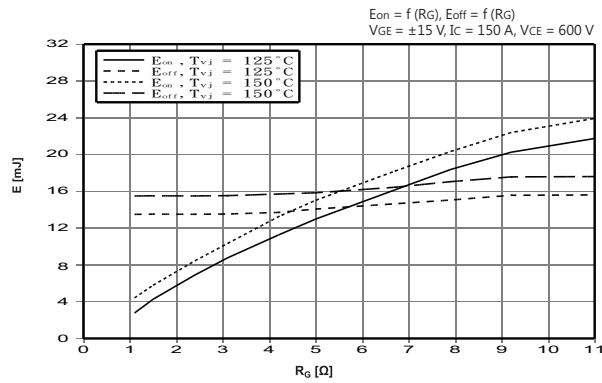


Fig.6 Transient thermal impedance IGBT, Inverter

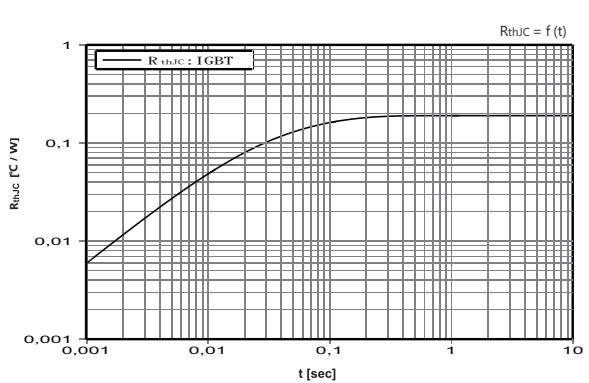


Fig.7 Reverse bias safe operating area IGBT, Inverter (RBSOA)

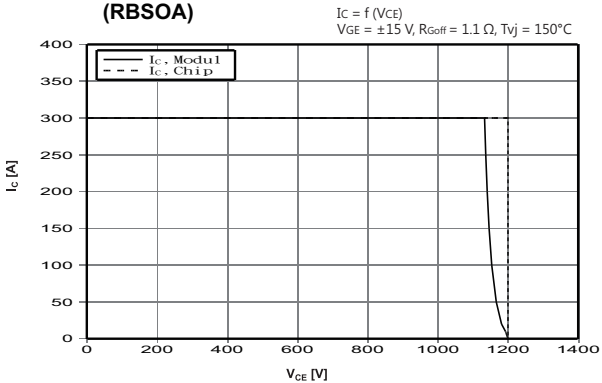
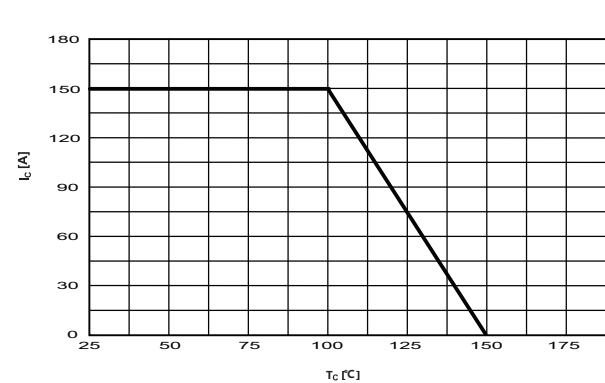


Fig.8 Output characteristic IGBT, Inverter (typical)





Typical Characteristics

Preliminary Data

Fig.9 Switching losses Diode, Inverter (typical)

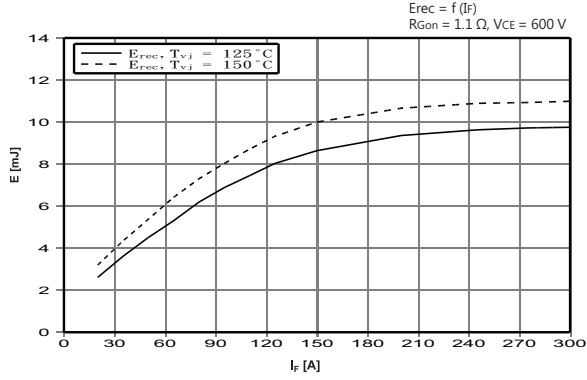


Fig.10 Switching losses Diode, Inverter (typical)

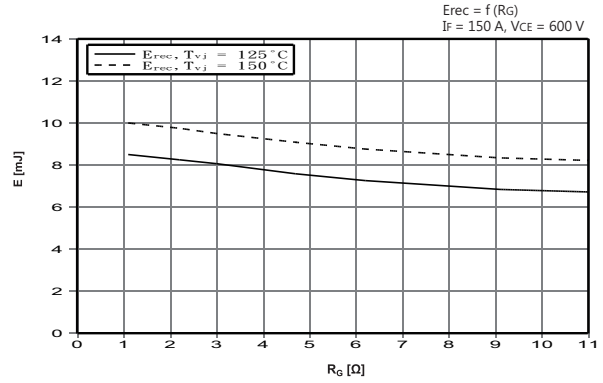


Fig.11 Transient thermal impedance Diode, Inverter

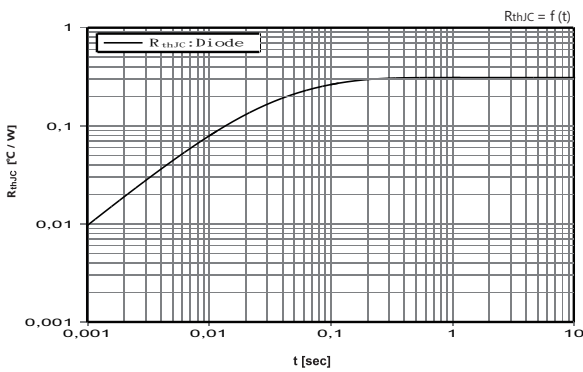
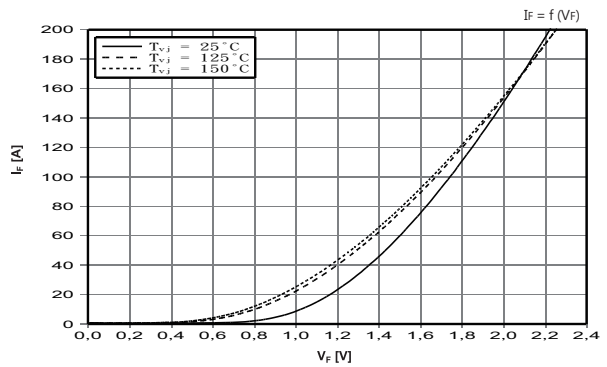


Fig.12 Forward characteristic of Diode, Inverter (typical)





Disclaimer

DACO Semiconductor reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to this document and any product described herein.

DACO Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does DACO Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages.

Purchasers is responsible for its products and applications using DACO Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by DACO Semiconductor. "Typical" parameters which may be provided in DACO Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts.

DACO Semiconductor products are not designed, authorized or warranted to be suitable for use in life support, life-critical or safety-critical systems or equipment, nor in applications where failure or malfunction of DACO Semiconductor's product can reasonably be expected to result in personal injury, death or severe property or environmental damage. DACO Semiconductor accept no liability for inclusion and/or use of DACO Semiconductor's products in such equipment or applications and therefore such inclusion and/or use is at the customer's own risk.

Purchasers buy or use DACO Semiconductor products for any such unintended or unauthorized application, Purchasers shall indemnify and hold DACO Semiconductor and its suppliers and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that DACO Semiconductor was negligent regarding the design or manufacture of the part.

No part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical, including photocopying and recording, or any information storage or retrieval system, or otherwise, without the prior written permission of DACO Semiconductor Co., Ltd.